

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2933	(semiconductor or die or dice or chip or IC) with (alignment or mark\$3 or cod\$3 or align\$4) with (encapsula\$4 or mold\$3 or resin)	USPAT	OR	ON	2008/04/22 13:14
L2	47	(semiconductor or die or dice or chip or IC) with (alignment near mark\$3) with (encapsula\$4 or mold\$3 or resin)	USPAT	OR	ON	2008/04/22 13:15
L3	1592	(semiconductor or die or dice or chip or IC) with (alignment or mark\$3) with (encapsula\$4 or mold\$3 or resin)	USPAT	OR	ON	2008/04/22 13:21
L4	26	(semiconductor or die or dice or chip or IC) with (alignment or mark\$3) with covered with (encapsula\$4 or mold\$3 or resin)	USPAT	OR	ON	2008/04/22 13:27
L5	29	(semiconductor or die or dice or chip or IC) with (alignment or mark\$3) with covered with (encapsula\$4 or mold\$3 or resin or transparent\$3 or translus\$4)	USPAT	OR	ON	2008/04/22 13:28
L6	39	("3751587"   "4148057"   "4375025"   "4585931"   "4638144"   "4707722"   "4719502"   "4753863"   "4861620"   "4945204"   "4964948"   "5030551"   "5157412"   "5206280"   "5262470"   "5268194"   "5302553"   "5329090"   "5346802"   "5348033"   "5357077"   "5373039"   "5413629"   "5445923"   "5493801"   "5741361"   "5761803"   "5817541"   "5822856"   "5887345").PN. OR ("6121067").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 13:32
L7	18	("4125418"   "5128283"   "5270255"   "5456756").PN. OR ("5738961").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 13:34
L8	49	(semiconductor or die or dice or chip or IC) with (alignment or mark\$3 or cod\$3 or align\$4) with covered with (encapsula\$4 or mold\$3 or resin)	USPAT	OR	ON	2008/04/22 13:42
L9	64	(semiconductor or die or dice or chip or IC) with (alignment or mark\$3 or cod\$3 or align\$4) with covered with (encapsula\$4 or mold\$3 or resin or transparent\$3 or translus\$4)	USPAT	OR	ON	2008/04/22 13:42

## EAST Search History

L10	854	(semiconductor or die or dice or chip or IC) with (alignment or mark\$3 or cod\$3 or align\$4) with formed with (encapsula\$4 or mold\$3 or resin or transparent\$3 or translus\$4)	USPAT	OR	ON	2008/04/22 13:49
L11	0	(semiconductor or die or dice or chip or IC) with (alignment or mark\$3 or cod\$3 or align\$4) with encapsulted with (encapsula\$4 or mold\$3 or resin or transparent\$3 or translus\$4)	USPAT	OR	ON	2008/04/22 13:50
L12	823	10 not 9	USPAT	OR	ON	2008/04/22 13:50
L13	4	("6121067"   "6143587").PN. OR ("6680220").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 13:59
L14	16	("3795845"   "4732646"   "5198963"   "5283468"   "5405810"   "5422435"   "5434453"   "5508565"   "5572068"   "5894172"   "6133637"   "6278193").PN. OR ("6476499").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 14:06
L15	15	("4027246"   "4095095"   "4419747"   "4825093"   "4962423"   "5175774"   "5463459"   "5475268"   "5557411"   "5560775"   "5651798").PN. OR ("5894172").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 14:29
L16	1245	3 not 10	USPAT	OR	ON	2008/04/22 14:34